

**DESCRIPTION**

The AM2302 is available in SOT-23S Package.

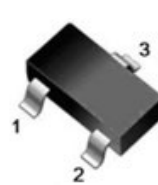
BVDSS	RDSON	ID
20V	45mΩ	3A

**ORDERING INFORMATION**

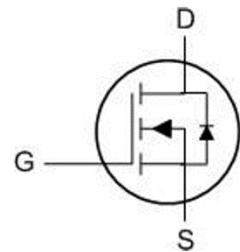
Package Type	Part Number	
SOT-23S SPQ: 3,000pcs/Reel	E3S	AM2302E3SR
		AM2302E3VSR
Note	R: Tape & Reel V: Halogen free Package	
AiT provides all RoHS products		

**APPLICATION**

- Green Device Available
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Advanced High Cell Density Trench Technology

**PIN DESCRIPTION**

SOT-23S



Pin#	Symbol	Function
1	G	Gate
2	S	Source
3	D	Drain

**ABSOLUTE MAXIMUM RATINGS**

T<sub>A</sub>=25°C Unless otherwise noted

V <sub>DS</sub> , Drain-Source Voltage	20V	
V <sub>GS</sub> , Gate-Source Voltage	±12V	
I <sub>D</sub> <sup>(1)</sup> , Continuous Drain Current, V <sub>GS</sub> @ 10V	T <sub>A</sub> =25°C	3A
	T <sub>A</sub> =70°C	1.20A
I <sub>DM</sub> <sup>(2)</sup> , Pulsed Drain Current	12A	
P <sub>D</sub> <sup>(3)</sup> , Total Power Dissipation	T <sub>A</sub> =25°C	0.85W
T <sub>J</sub> , Operating Junction Temperature Range	-55°C~+150°C	
T <sub>STG</sub> , Storage Temperature Range	-55°C~+150°C	
R <sub>θJA</sub> *, Thermal Resistance Junction-Ambient	162°C/W	

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

\* Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

**ELECTRICAL CHARACTERISTICS**T<sub>A</sub>=25°C, unless otherwise specified.

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	20	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20V, V <sub>GS</sub> =0V	-	-	1	μA
Gate to Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V	-	-	±100	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	0.40	0.70	1	V
Static Drain-Source On-Resistance*	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A	-	45	55	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =2A	-	62	85	
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1MHz	-	184	-	pF
Output Capacitance	C <sub>oss</sub>		-	38	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	28	-	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V I <sub>D</sub> =3A	-	2.70	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	0.40	-	
Gate-Drain ("Miller") Charge	Q <sub>gd</sub>		-	0.50	-	
<b>Switching Characteristics</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =3A, R <sub>GEN</sub> =3V, V <sub>GS</sub> =4.5V	-	8	-	ns
Turn-on Rise Time	t <sub>r</sub>		-	27	-	
Turn-off Delay Time	t <sub>d(off)</sub>		-	26	-	
Turn-off Fall Time	t <sub>f</sub>		-	33	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Maximum Continuous Drain to Source Diode Forward Current	I <sub>S</sub>	-	-	-	3	A
Maximum Pulsed Drain to Source Diode Forward Current	I <sub>SM</sub>	-	-	-	12	A
Drain to Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =3A	-	-	1.2	V

\* Pulse Test: PulseWidth≤300μs, Duty Cycle≤0.5%



## TYPICAL PERFORMANCE CHARACTERISTICS

Fig 1. Output Characteristics

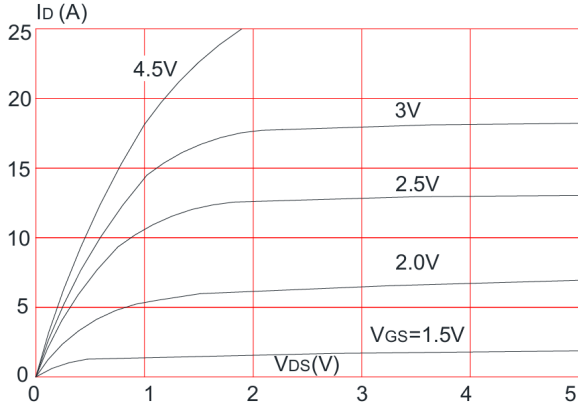


Fig 2. Typical Transfer Characteristics

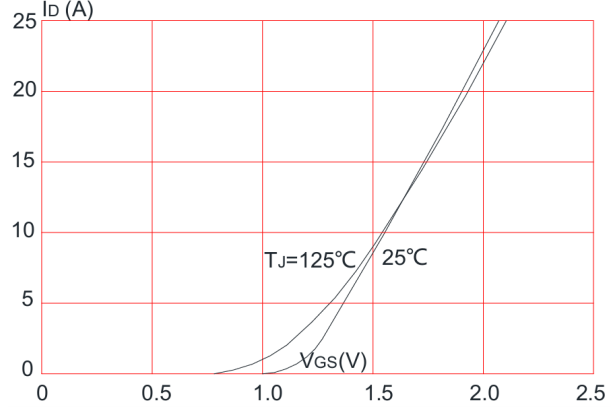


Fig 3. On-resistance vs. Drain Current

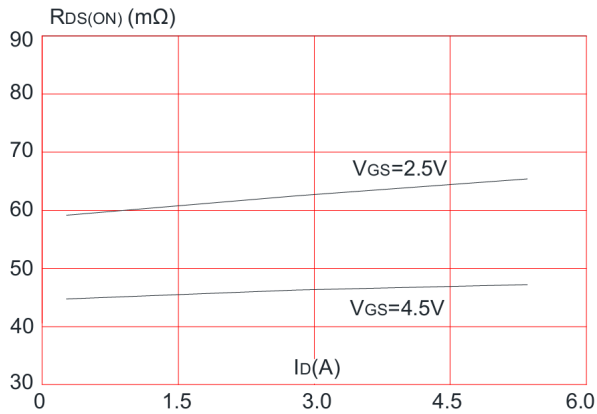


Fig 4. Body Diode Characteristics

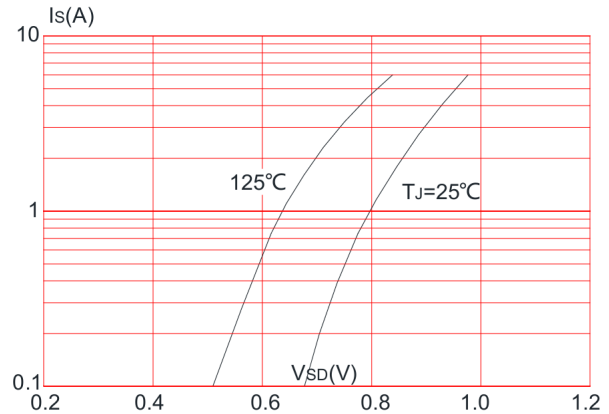


Fig 5. Gate Charge Characteristics

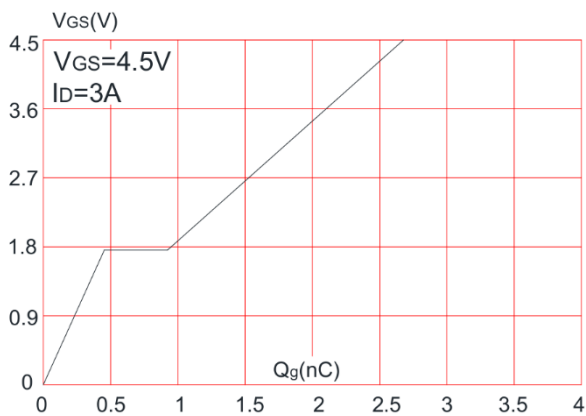


Fig 6. Capacitance Characteristics

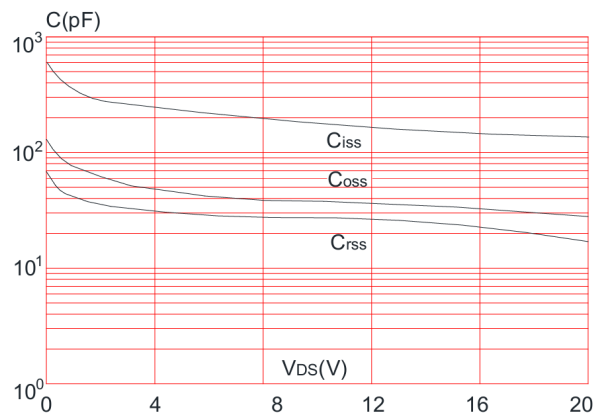




Fig 7. Normalized Breakdown Voltage vs. Junction Temperature

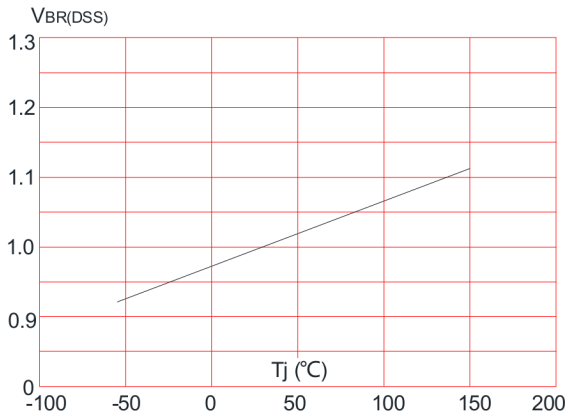


Fig 8. Normalized on Resistance vs. Junction Temperature

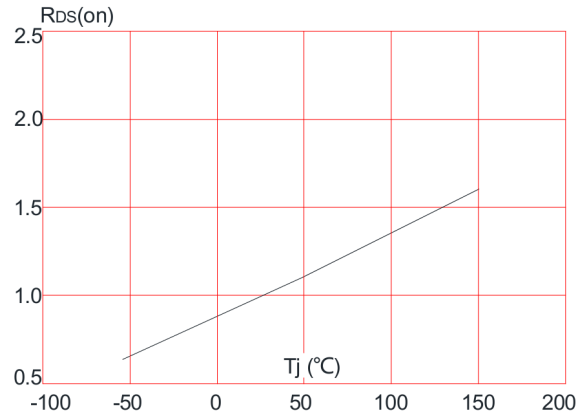


Fig 9. Maximum Safe Operating Area

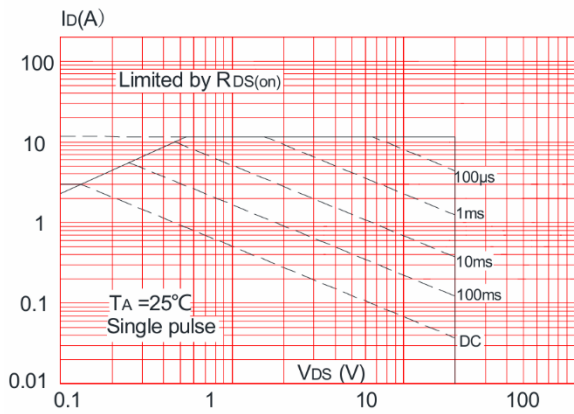


Fig 10. Maximum Continuous Drain Current

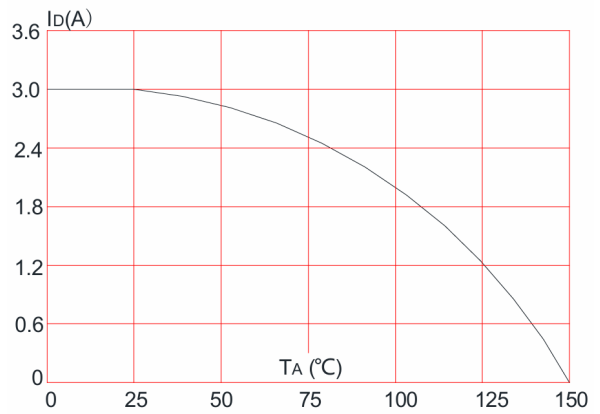
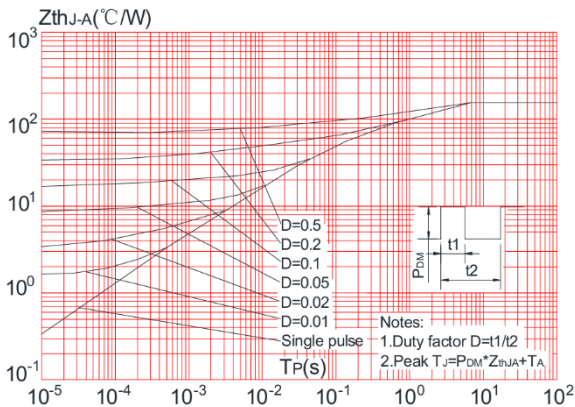


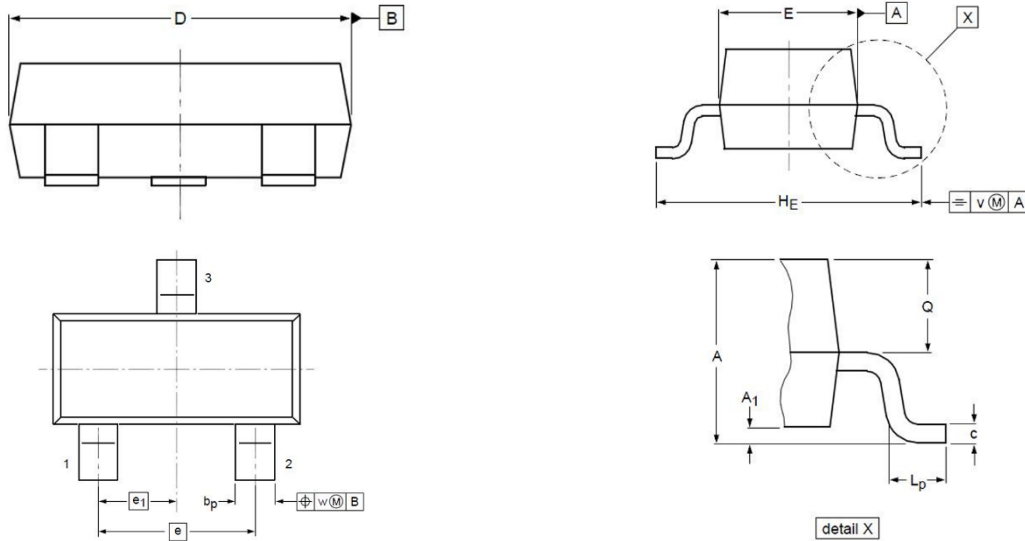
Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient





**PACKAGE INFORMATION**

Dimension in SOT-23 (Unit: mm)



Symbol	Millimeters (mm)	
	Min.	Max.
A	0.900	1.150
A1	0.010	0.100
$b_p$	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
e	1.900 TYP.	
$e_1$	0.950 TYP.	
$H_E$	2.250	2.550
$L_p$	0.300	0.500
Q	0.450	0.550
v	0.200 TYP.	
w	0.100 TYP.	



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